

# FC800L

# Hardware Design

**Wi-Fi&Bluetooth Module Series**

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## Safety Information

The following safety precautions must be observed during all phases of operation, such as usage, service or repair of any cellular terminal or mobile incorporating the module. Manufacturers of the cellular terminal should notify users and operating personnel of the following safety information by incorporating these guidelines into all manuals of the product. Otherwise, Quectel assumes no liability for customers' failure to comply with these precautions.



Full attention must be paid to driving at all times in order to reduce the risk of an accident. Using a mobile while driving (even with a handsfree kit) causes distraction and can lead to an accident. Please comply with laws and regulations restricting the use of wireless devices while driving.



Switch off the cellular terminal or mobile before boarding an aircraft. The operation of wireless appliances in an aircraft is forbidden to prevent interference with communication systems. If there is an Airplane Mode, it should be enabled prior to boarding an aircraft. Please consult the airline staff for more restrictions on the use of wireless devices on an aircraft.



Wireless devices may cause interference on sensitive medical equipment, so please be aware of the restrictions on the use of wireless devices when in hospitals, clinics or other healthcare facilities.



Cellular terminals or mobiles operating over radio signal and cellular network cannot be guaranteed to connect in certain conditions, such as when the mobile bill is unpaid or the (U)SIM card is invalid. When emergent help is needed in such conditions, use emergency call if the device supports it. In order to make or receive a call, the cellular terminal or mobile must be switched on in a service area with adequate cellular signal strength. In an emergency, the device with emergency call function cannot be used as the only contact method considering network connection cannot be guaranteed under all circumstances.



The cellular terminal or mobile contains a transceiver. When it is ON, it receives and transmits radio frequency signals. RF interference can occur if it is used close to TV sets, radios, computers or other electric equipment.



In locations with explosive or potentially explosive atmospheres, obey all posted signs and turn off wireless devices such as mobile phone or other cellular terminals. Areas with explosive or potentially explosive atmospheres include fuelling areas, below decks on boats, fuel or chemical transfer or storage facilities, and areas where the air contains chemicals or particles such as grain, dust or metal powders.

# About the Document

## Revision History

| Version | Date       | Author      | Description                                                                                                                                                                                                                                                                 |
|---------|------------|-------------|-----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| -       | 2021-11-08 | Macky XU    | Creation of the document                                                                                                                                                                                                                                                    |
| 1.0.0   | 2021-11-08 | Macky XU    | Preliminary                                                                                                                                                                                                                                                                 |
| 1.0.1   | 2022-04-13 | Arrow HUANG | Preliminary:<br>1. Updated operating temperature.                                                                                                                                                                                                                           |
| 1.0.2   | 2022-04-27 | Arrow HUANG | Preliminary:<br>1. Updated operating mode (Table 2, Table 29)                                                                                                                                                                                                               |
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## Contents

|                                                                 |           |
|-----------------------------------------------------------------|-----------|
| Safety Information.....                                         | 3         |
| About the Document.....                                         | 4         |
| Contents.....                                                   | 5         |
| Table Index .....                                               | 7         |
| Figure Index.....                                               | 8         |
| <b>1 Introduction .....</b>                                     | <b>9</b>  |
| 1.1. Special Mark.....                                          | 14        |
| <b>2 Product Overview.....</b>                                  | <b>15</b> |
| 2.1. General Description.....                                   | 15        |
| 2.2. Key Features .....                                         | 15        |
| 2.3. EVB .....                                                  | 17        |
| <b>3 Application Interfaces.....</b>                            | <b>18</b> |
| 3.1. General Description.....                                   | 18        |
| 3.2. Pin Assignment .....                                       | 19        |
| 3.3. Pin Description .....                                      | 20        |
| 3.4. Power Supply .....                                         | 22        |
| 3.5. WLAN Application Interface.....                            | 23        |
| 3.5.1. WLAN_WAKE .....                                          | 24        |
| 3.5.2. SDIO Interface.....                                      | 24        |
| 3.6. Bluetooth Application Interface .....                      | 25        |
| 3.6.1. BT_EN.....                                               | 26        |
| 3.6.2. UART Interface.....                                      | 26        |
| 3.6.3. BT_WAKE_HOST* and HOST_WAKE_BT* .....                    | 27        |
| 3.6.4. PCM Interface* .....                                     | 27        |
| 3.7. Other Interfaces.....                                      | 28        |
| 3.7.1. RTC_CLK.....                                             | 28        |
| 3.7.2. CHIP_EN.....                                             | 29        |
| 3.8. RF Antenna Interfaces.....                                 | 30        |
| 3.8.1. Operating Frequency.....                                 | 30        |
| 3.8.2. Pin Definition of RF Antenna Interface .....             | 30        |
| 3.8.3. Reference Design of RF Antenna Interfaces .....          | 30        |
| 3.8.4. Reference Design of RF Layout .....                      | 32        |
| 3.8.5. Antenna Requirements.....                                | 33        |
| 3.8.6. Recommended RF Connector for Antenna Installation .....  | 34        |
| <b>4 Reliability, Radio and Electrical Characteristic .....</b> | <b>36</b> |
| 4.1. General Description.....                                   | 36        |
| 4.2. Electrical Characteristics .....                           | 36        |

|          |                                                   |           |
|----------|---------------------------------------------------|-----------|
| 4.3.     | I/O Interface Characteristics .....               | 37        |
| 4.4.     | Current Consumption .....                         | 38        |
| 4.5.     | RF Performances .....                             | 40        |
| 4.5.1.   | Wi-Fi Performance .....                           | 40        |
| 4.5.2.   | Bluetooth Performance.....                        | 42        |
| 4.6.     | Electrostatic Discharge .....                     | 43        |
| <b>5</b> | <b>Mechanical Information .....</b>               | <b>44</b> |
| 5.1.     | Mechanical Dimensions.....                        | 44        |
| 5.2.     | Recommended Footprint .....                       | 45        |
| 5.3.     | Top and Bottom Views .....                        | 46        |
| <b>6</b> | <b>Storage, Manufacturing and Packaging .....</b> | <b>47</b> |
| 6.1.     | Storage Conditions .....                          | 47        |
| 6.2.     | Manufacturing and Soldering.....                  | 48        |
| 6.3.     | Packaging Specifications.....                     | 50        |
| 6.3.1.   | Carrier Tape .....                                | 50        |
| 6.3.2.   | Plastic Reel .....                                | 51        |
| 6.3.3.   | Packaging Process.....                            | 52        |
| <b>7</b> | <b>Appendix References .....</b>                  | <b>53</b> |

## Table Index

|                                                                                                   |    |
|---------------------------------------------------------------------------------------------------|----|
| Table 1: Special Mark.....                                                                        | 14 |
| Table 2: Key Features .....                                                                       | 15 |
| Table 3: I/O Parameters Definition .....                                                          | 20 |
| Table 4: Pin Description .....                                                                    | 20 |
| Table 5: Definition of Power Supply and GND Pins.....                                             | 22 |
| Table 6: Pin Definition of WLAN_WAKE .....                                                        | 24 |
| Table 7: Pin Definition of SDIO Interface.....                                                    | 24 |
| Table 8: Pin Definition of BT_EN.....                                                             | 26 |
| Table 9: Pin Definition of UART Interface.....                                                    | 26 |
| Table 10: Pin Definition of BT_WAKEUP_HOST and HOST_WAKEUP_BT .....                               | 27 |
| Table 11: Pin Definition of PCM Interface .....                                                   | 28 |
| Table 12: Pin Definition of RTC_CLK .....                                                         | 28 |
| Table 13: Pin Definition of CHIP_EN.....                                                          | 29 |
| Table 14: Conducted RF Output Power at 2.4 GHz .....                                              | 40 |
| Table 15: Conducted RF Output Power at 5 GHz .....                                                | 40 |
| Table 16: Conducted RF Receiving Sensitivity at 2.4 GHz .....                                     | 41 |
| Table 17: Conducted RF Receiving Sensitivity at 5 GHz .....                                       | 41 |
| Table 18: Electrostatics Discharge Characteristics (25 °C, 45 % Relative Humidity; Unit: kV)..... | 43 |
| Table 19: Recommended Thermal Profile Parameters .....                                            | 49 |
| Table 20: Carrier Tape Dimension Table (Unit: mm).....                                            | 50 |
| Table 21: Plastic Reel Dimension Table (Unit: mm).....                                            | 51 |
| Table 22: Related Documents.....                                                                  | 53 |
| Table 23: Terms and Abbreviations.....                                                            | 53 |

## Figure Index

|                                                                                           |    |
|-------------------------------------------------------------------------------------------|----|
| Figure 2: Pin Assignment (Top View) .....                                                 | 19 |
| Figure 3: Power up Timing .....                                                           | 23 |
| Figure 4: WLAN Application Interface Connection .....                                     | 23 |
| Figure 5: SDIO Interface Connection .....                                                 | 25 |
| Figure 6: Block Diagram of Bluetooth Application Interface Connection .....               | 26 |
| Figure 7: Reference Design for UART Interface Connection.....                             | 27 |
| Figure 8: PCM Interface Connection .....                                                  | 28 |
| Figure 9: Reference Circuit for RF Antenna Interfaces.....                                | 31 |
| Figure 10: Microstrip Design on a 2-layer PCB .....                                       | 32 |
| Figure 11: Coplanar Waveguide Design on a 2-layer PCB .....                               | 32 |
| Figure 12: Coplanar Waveguide Design on a 4-layer PCB (Layer 3 as Reference Ground) ..... | 32 |
| Figure 13: Coplanar Waveguide Design on a 4-layer PCB (Layer 4 as Reference Ground) ..... | 33 |
| Figure 14: Dimensions of the U.FL-R-SMT Connector (Unit: mm) .....                        | 34 |
| Figure 15: Mechanicals of U.F.L-LP Connectors (Unit: mm) .....                            | 35 |
| Figure 16: Space Factor of Mated Connector (Unit: mm).....                                | 35 |
| Figure 17: Top and Side Dimensions (Top and Side View).....                               | 44 |
| Figure 18: Recommended Footprint (Top View).....                                          | 45 |
| Figure 19: Top and Bottom Views of the Module.....                                        | 46 |
| Figure 20: Recommended Reflow Soldering Thermal Profile.....                              | 48 |
| Figure 21: Carrier Tape Dimension Drawing .....                                           | 50 |
| Figure 22: Plastic Reel Dimension Drawing .....                                           | 51 |
| Figure 23: Packaging Process.....                                                         | 52 |

# 1 Introduction

This document defines the FC800L and describes its air interfaces and hardware interfaces which are connected with your application.

This equipment has been tested and found to comply with the limits for a Class B digital device, pursuant to Part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference in a residential installation. This equipment generates, uses and can radiate radio frequency energy and, if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. However, there is no guarantee that interference will not occur in a particular installation.

If this equipment does cause harmful interference to radio or television reception, which can be determined by turning the equipment off and on, the user is encouraged to try to correct the interference by one or more of the following measures:

- Reorient or relocate the receiving antenna.
- Increase the separation between the equipment and receiver.
- Connect the equipment into an outlet on a circuit different from that to which the receiver is connected.
- Consult the dealer or an experienced radio/TV technician for help.

This device complies with FCC radiation exposure limits set forth for an uncontrolled environment. In order to avoid the possibility of exceeding the FCC radio frequency exposure limits, human proximity to the antenna shall not be less than 20cm (8 inches) during normal operation.

This transmitter must not be co-located or operating in conjunction with any other antenna or transmitter.

Any changes or modifications not expressly approved by the party responsible for compliance could void the user's authority to operate this equipment. This transmitter must not be co-located or operating in conjunction with any other antenna or transmitter.

## Important Notice to OEM integrators

1. This module is limited to OEM installation ONLY.
2. This module is limited to installation in fixed applications, according to Part 2.1091(b).
3. The separate approval is required for all other operating configurations, including portable configurations with respect to Part 2.1093 and different antenna configurations
4. For FCC Part 15.31 (h) and (k): The host manufacturer is responsible for additional testing to verify compliance as a composite system. When testing the host device for compliance with Part 15 Subpart B, the host manufacturer is required to show compliance with Part 15 Subpart B while the transmitter module(s) are installed and operating. The modules should be transmitting and the evaluation should confirm that the module's intentional emissions are compliant (i.e. fundamental and out of band

emissions). The host manufacturer must verify that there are no additional unintentional emissions other than what is permitted in Part 15 Subpart B or emissions are compliant with the transmitter(s) rule(s).

The Grantee will provide guidance to the host manufacturer for Part 15 B requirements if needed.

Important Note notice that any deviation(s) from the defined parameters of the antenna trace, as described by the instructions, require that the host product manufacturer must notify to Quectel Wireless Solutions Co., Ltd that they wish to change the antenna trace design. In this case, a Class II permissive change application is required to be filed by the USI, or the host manufacturer can take responsibility through the change in FCC ID (new application) procedure followed by a Class II permissive change application.

#### End Product Labeling

When the module is installed in the host device, the FCC/IC ID label must be visible through a window on the final device or it must be visible when an access panel, door or cover is easily re-moved. If not, a second label must be placed on the outside of the final device that contains the following text: "Contains FCC ID: XMR202207FC800L"

The FCC ID can be used only when all FCC compliance requirements are met.

#### Antenna Installation

- (1) The antenna must be installed such that 20 cm is maintained between the antenna and users,
- (2) The transmitter module may not be co-located with any other transmitter or antenna.
- (3) Only antennas of the same type and with equal or less gains as shown below may be used with this module. Other types of antennas and/or higher gain antennas may require additional authorization for operation.
- (4) The max allowed antenna gain is WIFI 2.4G/BT 0.52dBi; WIFI 5G 0.66 dBi for external antenna.

In the event that these conditions cannot be met (for example certain laptop configurations or co-location with another transmitter), then the FCC authorization is no longer considered valid and the FCC ID/IC ID cannot be used on the final product. In these circumstances, the OEM integrator will be responsible for re-evaluating the end product (including the transmitter) and obtaining a separate FCC/IC authorization.

#### Manual Information to the End User

The OEM integrator has to be aware not to provide information to the end user regarding how to install or remove this RF module in the user's manual of the end product which integrates this module. The end user manual shall include all required regulatory information/warning as show in this manual.

This device complies with part 15 of the FCC Rules. Operation is subject to the following two conditions:

- (1) This device may not cause harmful interference, and
- (2) this device must accept any interference received, including interference that may cause undesired operation.

This device complies with ISSED's licence-exempt RSSs. Operation is subject to the following two conditions:

- (1) This device may not cause harmful interference, and
- (2) this device must accept any interference received, including interference that may cause undesired operation.

Le présent appareil est conforme aux CNR d' ISSED applicables aux appareils radio exempts de licence. L'exploitation est autorisée aux deux conditions suivantes : (1) le dispositif ne doit pas produire de brouillage préjudiciable, et (2) ce dispositif doit accepter tout brouillage reçu, y compris un brouillage susceptible de provoquer un fonctionnement indésirable.

**Radiation Exposure Statement:**

This equipment complies with ISSED radiation exposure limits set forth for an uncontrolled environment. This equipment should be installed and operated with minimum distance 20cm between the radiator & your body.

**Déclaration d'exposition aux radiations:**

Cet équipement est conforme aux limites d'exposition aux rayonnements ISSED établies pour un environnement non contrôlé. Cet équipement doit être installé et utilisé avec un minimum de 20 cm de distance entre la source de rayonnement et votre corps.

This device is intended only for OEM integrators under the following conditions: (For module device use)

- 1) The antenna must be installed such that 20 cm is maintained between the antenna and users, and
- 2) The transmitter module may not be co-located with any other transmitter or antenna.

As long as 2 conditions above are met, further transmitter test will not be required. However, the OEM integrator is still responsible for testing their end-product for any additional compliance requirements required with this module installed.

Cet appareil est conçu uniquement pour les intégrateurs OEM dans les conditions suivantes: (Pour utilisation de dispositif module)

- 1) L'antenne doit être installée de telle sorte qu'une distance de 20 cm est respectée entre l'antenne et les utilisateurs, et
- 2) Le module émetteur peut ne pas être coïmplanté avec un autre émetteur ou antenne.

Tant que les 2 conditions ci-dessus sont remplies, des essais supplémentaires sur l'émetteur ne seront pas nécessaires. Toutefois, l'intégrateur OEM est toujours responsable des essais sur son produit final pour toutes exigences de conformité supplémentaires requis pour ce module installé.

**IMPORTANT NOTE:**

In the event that these conditions can not be met (for example certain laptop configurations or co- location with another transmitter), then the Canada authorization is no longer considered valid and the IC ID can not be used on the final product. In these circumstances, the OEM integrator will be responsible for re-evaluating the end product (including the transmitter) and obtaining a separate Canada authorization.

**NOTE IMPORTANTE:**

Dans le cas où ces conditions ne peuvent être satisfaites (par exemple pour certaines configurations d'ordinateur portable ou de certaines co-localisation avec un autre émetteur), l'autorisation du Canada n'est plus considéré comme valide et l'ID IC ne peut pas être utilisé sur le produit final. Dans ces circonstances, l'intégrateur OEM sera chargé de réévaluer le produit final (y compris l'émetteur) et l'obtention d'une autorisation distincte au Canada.

End Product Labeling

This transmitter module is authorized only for use in device where the antenna may be installed such that 20 cm may be maintained between the antenna and users. The final end product must be labeled in a visible area with the following:

“Contains IC: 10224A-2022FC800L”.

#### Plaque signalétique du produit final

Ce module émetteur est autorisé uniquement pour une utilisation dans un dispositif où l'antenne peut être installée de telle sorte qu'une distance de 20cm peut être maintenue entre l'antenne et les utilisateurs. Le produit final doit être étiqueté dans un endroit visible avec l'inscription suivante: "Contient des IC: 10224A-2022FC800L ".

#### Manual Information To the End User

The OEM integrator has to be aware not to provide information to the end user regarding how to install or remove this RF module in the user's manual of the end product which integrates this module. The end user manual shall include all required regulatory information/warning as show in this manual.

#### Manuel d'information à l'utilisateur final

L'intégrateur OEM doit être conscient de ne pas fournir des informations à l'utilisateur final quant à la façon d'installer ou de supprimer ce module RF dans le manuel de l'utilisateur du produit final qui intègre ce module.

Le manuel de l'utilisateur final doit inclure toutes les informations réglementaires requises et avertissements comme indiqué dans ce manuel.

RSS-247 Section 6.4 (5) (6) (for local area network devices, 5GHz)

The device could automatically discontinue transmission in case of absence of information to transmit, or operational failure.

Note that this is not intended to prohibit transmission of control or signaling information or the use of repetitive codes where required by the technology.

Caution:

- i) The device for operation in the band 5150–5250 MHz is only for indoor use to reduce the potential for harmful interference to co-channel mobile satellite systems;
- ii) where applicable, antenna type(s), antenna models(s), and worst-case tilt angle(s) necessary to remain compliant with the e.i.r.p. elevation mask requirement set forth in section 6.2.2.3 shall be clearly indicated.

L'appareil peut interrompre automatiquement la transmission en cas d'absence d'informations à transmettre ou de panne opérationnelle. Notez que ceci n'est pas destiné à interdire la transmission d'informations de contrôle ou de signalisation ou l'utilisation de codes répétitifs lorsque cela est requis par la technologie.

Avertissement:

- i) Le dispositif utilisé dans la bande 5150-5250 MHz est réservé à une utilisation en intérieur afin de réduire le risque de brouillage préjudiciable aux systèmes mobiles par satellite dans le même canal;
- ii) lorsqu'il y a lieu, les types d'antennes (s'il y en a plusieurs), les numéros de modèle de l'antenne et les pires angles d'inclinaison nécessaires pour rester conforme à l'exigence de la p.i.r.e. applicable au masque d'élévation, énoncée à la section 6.2.2.3, doivent être clairement indiqués.

- i. for devices with detachable antenna(s), the maximum antenna gain permitted for devices in the bands 5250-5350 MHz and 5470-5725 MHz shall be such that the equipment still complies with the e.i.r.p. limit
- ii. for devices with detachable antenna(s), the maximum antenna gain permitted for devices in the band 5725-5850 MHz shall be such that the equipment still complies with the e.i.r.p. limits as appropriate;

and

iii. where applicable, antenna type(s), antenna models(s), and worst-case tilt angle(s) necessary to remain compliant with the e.i.r.p. elevation mask requirement set forth in section 6.2.2.3 shall be clearly indicated.

## 1.1. Special Mark

Table 1: Special Mark

| Mark | Definition                                                                                                                                                                                                                                                                                                                                                                |
|------|---------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| *    | Unless otherwise specified, when an asterisk (*) is used after a function, feature, interface, pin name, AT command, or argument, it indicates that the function, feature, interface, pin, AT command, or argument is under development and currently not supported; and the asterisk (*) after a model indicates that the sample of such model is currently unavailable. |

## 2 Product Overview

### 2.1. General Description

FC800L is a Wi-Fi and Bluetooth module with low power consumption. It is a single-die WLAN (Wireless Local Area Network) and Bluetooth combo solution supporting IEEE 802.11a/b/g/n/ac 2.4/5 GHz WLAN standards and Bluetooth 5.0 standard, which enables seamless integration of WLAN and Bluetooth low energy technologies.

With a low-power SDIO 3.0 interface for WLAN, a UART and a PCM interface for Bluetooth. FC800L can provide WLAN and Bluetooth functions.

### 2.2. Key Features

The following table describes the key features of FC800L.

**Table 2: Key Features**

| Features                | Details                                                                                                                                                                                                                                                                                                        |
|-------------------------|----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| Power Supply            | <ul style="list-style-type: none"> <li>● <b>VBAT power supply:</b><br/>Supply voltage range: 2.97–3.63 V<br/>Typical supply voltage: 3.3 V</li> <li>● <b>VDDIO power supply:</b><br/>Supply voltage range: 1.62–1.98 V<br/>Typical supply voltage: 1.8 V</li> </ul>                                            |
| Operating Frequency     | <ul style="list-style-type: none"> <li>● 2.4 GHz WLAN: 2.400–2.4835 GHz</li> <li>● 5 GHz WLAN: 5.15–5.85 GHz</li> <li>● Bluetooth: 2.402–2.480 GHz</li> </ul>                                                                                                                                                  |
| Transmission Data Rates | <ul style="list-style-type: none"> <li>● 802.11b: 1 Mbps, 2 Mbps, 5.5 Mbps, 11 Mbps</li> <li>● 802.11a/g: 6 Mbps, 9 Mbps, 12 Mbps, 18 Mbps, 24 Mbps, 36 Mbps, 48 Mbps, 54 Mbps</li> <li>● 802.11n: HT20 (MCS0-7), HT40 (MCS0-7)</li> <li>● 802.11ac: VHT20 (MCS0-8), VHT40 (MCS0-9), VHT80 (MCS0-9)</li> </ul> |

|                                 |                                                                                                                                                                                                                                                                                                                                                                                                                                          |
|---------------------------------|------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| Transmitting Power              | <ul style="list-style-type: none"> <li>● <b>2.4 GHz</b><br/>802.11b/11 Mbps: 16.0 ±2 dBm<br/>802.11g/54 Mbps: 15.0 ±2 dBm<br/>802.11n/HT20 MCS7: 14 ±2 dBm<br/>802.11n/HT40 MCS7: 14 ±2 dBm</li> <li>● <b>5 GHz</b><br/>802.11a/54 Mbps: 15 ±3 dBm<br/>802.11n/HT20 MCS7: 14 ±3 dBm<br/>802.11n/HT40 MCS7: 14 ±3 dBm<br/>802.11ac/VHT20 MCS8: 13 ±3 dBm<br/>802.11ac/VHT40 MCS9: 12 ±3 dBm<br/>802.11ac/VHT80 MCS9: 11 ±3 dBm</li> </ul> |
| Operation Mode                  | STA                                                                                                                                                                                                                                                                                                                                                                                                                                      |
| Modulation                      | CCK, BPSK, QPSK, 16QAM, 64QAM, 256QAM                                                                                                                                                                                                                                                                                                                                                                                                    |
| WLAN Application Interface      | SDIO 3.0                                                                                                                                                                                                                                                                                                                                                                                                                                 |
| Bluetooth Application Interface | UART and PCM                                                                                                                                                                                                                                                                                                                                                                                                                             |
| RF Antenna Interfaces           | <ul style="list-style-type: none"> <li>● ANT_WIFI</li> <li>● ANT_BT</li> </ul>                                                                                                                                                                                                                                                                                                                                                           |
| Physical Characteristics        | <ul style="list-style-type: none"> <li>● Size: (13 ±0.15) mm × (15 ±0.15) mm × (2.2 ±0.2) mm</li> <li>● Package: LCC</li> <li>● Weight: about 0.8g</li> </ul>                                                                                                                                                                                                                                                                            |
| Temperature Range               | <ul style="list-style-type: none"> <li>● Operating temperature range: 0 °C to +70 °C <sup>1</sup></li> <li>● Storage temperature range: -40 °C to +95 °C</li> </ul>                                                                                                                                                                                                                                                                      |
| RoHS                            | All hardware components are fully compliant with EU RoHS directive                                                                                                                                                                                                                                                                                                                                                                       |

<sup>1</sup> Within operating temperature range, the module is IEEE compliant.

## 2.3. EVB

Quectel supplies an evaluation board (FC800L-M.2) with accessories to control or test the module.

# 3 Application Interfaces

## 3.1. General Description

FC800L is equipped with 50 LCC pins. The subsequent chapters will provide a detailed introduction to the following interfaces and pins of the module:

- Power supply
- WLAN application interface
- Bluetooth application interface
- RF antenna interfaces
- Other interfaces

## 3.2. Pin Assignment

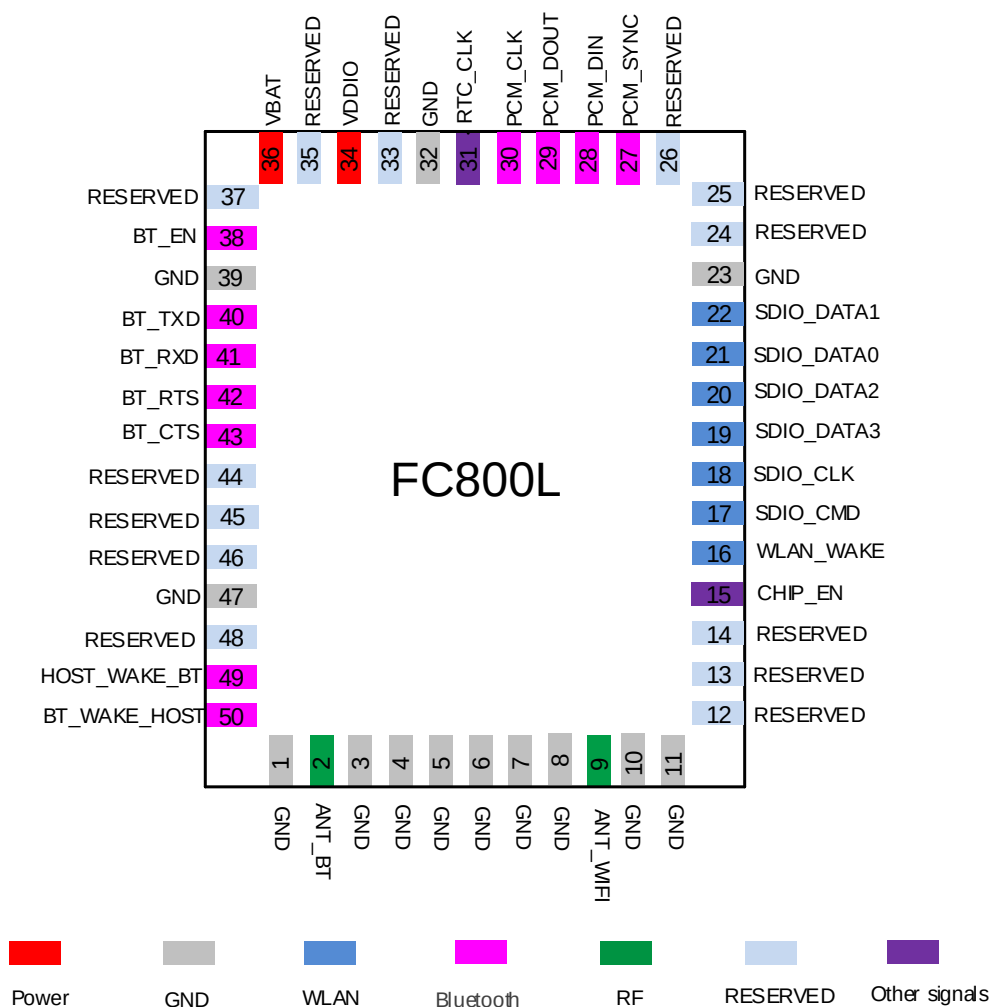


Figure 1: Pin Assignment (Top View)

### NOTE

Keep all RESERVED pins open.

### 3.3. Pin Description

Table 3: I/O Parameters Definition

| Type | Description          |
|------|----------------------|
| AI   | Analog Input         |
| AO   | Analog Input         |
| AIO  | Analog Input/Output  |
| DI   | Digital Input        |
| DO   | Digital Output       |
| DIO  | Digital Input/Output |
| PI   | Power Input          |
| PO   | Power Output         |

Table 4: Pin Description

| Power Supply               |                               |     |                                                       |                                                          |
|----------------------------|-------------------------------|-----|-------------------------------------------------------|----------------------------------------------------------|
| Pin Name                   | Pin No.                       | I/O | Description                                           | Comment                                                  |
| VBAT                       | 36                            | PI  | Power supply for the module                           | It must be provided with sufficient current up to 1.2 A. |
| VDDIO                      | 34                            | PI  | Power supply for module's I/O pins                    | VDDIO only support 1.8 V                                 |
| GND                        | 1, 3-8, 10-11, 23, 32, 39, 47 |     |                                                       |                                                          |
| WLAN Application Interface |                               |     |                                                       |                                                          |
| Pin Name                   | Pin No.                       | I/O | Description                                           | Comment                                                  |
| WLAN_WAKE                  | 16                            | DO  | Wake up the host by WLAN, and SDIO interrupt function | VDDIO power domain                                       |
| SDIO_CMD                   | 17                            | DIO | SDIO command                                          |                                                          |
| SDIO_CLK                   | 18                            | DI  | SDIO clock                                            |                                                          |

| SDIO_DATA3                             | 19      | DIO | SDIO data bit 3                |                                    |
|----------------------------------------|---------|-----|--------------------------------|------------------------------------|
| SDIO_DATA2                             | 20      | DIO | SDIO data bit 2                |                                    |
| SDIO_DATA0                             | 21      | DIO | SDIO data bit 0                |                                    |
| SDIO_DATA1                             | 22      | DIO | SDIO data bit 1                |                                    |
| <b>Bluetooth Application Interface</b> |         |     |                                |                                    |
| Pin Name                               | Pin No. | I/O | Description                    | Comment                            |
| PCM_SYNC*                              | 27      | DI  | PCM data frame sync            |                                    |
| PCM_DIN*                               | 28      | DI  | PCM data input                 |                                    |
| PCM_DOUT*                              | 29      | DO  | PCM data output                | VDDIO power domain                 |
| PCM_CLK*                               | 30      | DI  | PCM clock                      |                                    |
| BT_EN                                  | 38      | DI  | Bluetooth enable control       | Active high.<br>VDDIO power domain |
| BT_TXD                                 | 40      | DO  | Bluetooth UART transmit        |                                    |
| BT_RXD                                 | 41      | DI  | Bluetooth UART receive         |                                    |
| BT_RTS                                 | 42      | DO  | Bluetooth UART request to send |                                    |
| BT_CTS                                 | 43      | DI  | Bluetooth UART clear to send   | VDDIO power domain                 |
| HOST_WAKE_BT*                          | 49      | DI  | Host wakes up Bluetooth        |                                    |
| BT_WAKE_HOST*                          | 50      | DO  | Bluetooth wakes up host        |                                    |
| <b>Other Interfaces</b>                |         |     |                                |                                    |
| Pin Name                               | Pin No. | I/O | Description                    | Comment                            |

|                       |                                     |     |                                 |                                                                                                     |
|-----------------------|-------------------------------------|-----|---------------------------------|-----------------------------------------------------------------------------------------------------|
| RTC_CLK               | 31                                  | DI  | External 32.768 kHz clock input | VDDIO power domain                                                                                  |
| CHIP_EN               | 15                                  | DI  | Module enable pin               | Pull up to VDDIO internally through a 4.7 kΩ resistor, high level by default.<br>VDDIO power domain |
| RF Antenna Interfaces |                                     |     |                                 |                                                                                                     |
| Pin Name              | Pin No.                             | I/O | Description                     | Comment                                                                                             |
| ANT_BT                | 2                                   | AIO | Bluetooth antenna interface     | 50 Ω impedance.                                                                                     |
| ANT_WIFI              | 9                                   | AIO | Wi-Fi antenna interface         |                                                                                                     |
| RESERVED Interfaces   |                                     |     |                                 |                                                                                                     |
| Pin Name              | Pin No.                             | I/O | Description                     | Comment                                                                                             |
| RESERVED              | 12–14, 24–26, 33, 35, 37, 44–46, 48 |     |                                 | Keep these pins open.                                                                               |

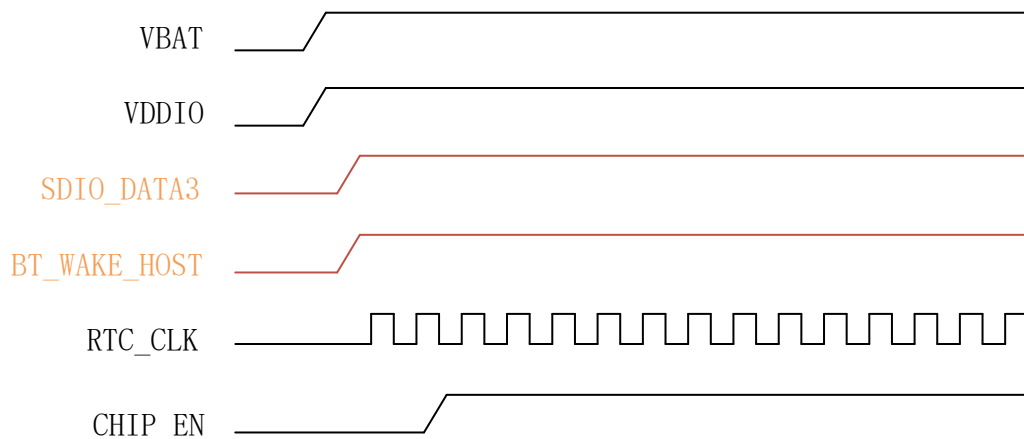
### 3.4. Power Supply

The following table shows the power supply pins and ground pins of FC800L.

**Table 5: Definition of Power Supply and GND Pins**

| Pin Name | Pin No.                       | Description                        | Min. | Typ. | Max. | Unit |
|----------|-------------------------------|------------------------------------|------|------|------|------|
| VBAT     | 36                            | Power supply for the module        | 2.97 | 3.3  | 3.63 | V    |
| VDDIO    | 34                            | Power supply for module's I/O pins | 1.62 | 1.8  | 1.98 | V    |
| GND      | 1, 3–8, 10–11, 23, 32, 39, 47 |                                    |      |      |      |      |

FC800L is powered by VBAT and VDDIO, and VBAT is recommended to use a power supply chip with maximum output current more than 1.2 A. The following figure shows the recommended power up timing of FC800L.



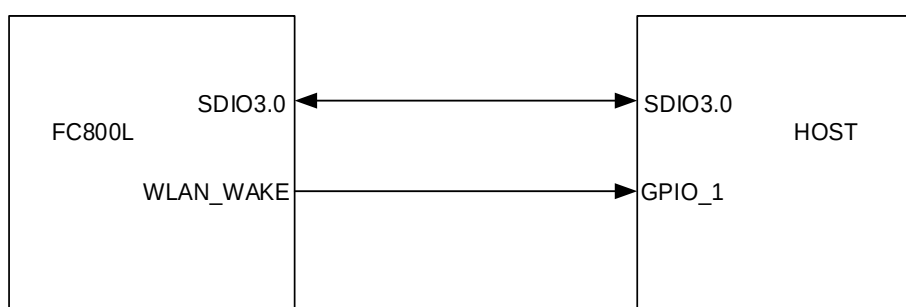
**Figure 2: Power up Timing**

**NOTE**

1. VBAT should be up before or at the same time as VDDIO. VDDIO should not be present first or be held high before VBAT is high.
2. RTC\_CLK must held stable before CHIP\_EN held high.

### 3.5. WLAN Application Interface

The following figure shows the WLAN application interface connection between FC800L and the host.



**Figure 3: WLAN Application Interface Connection**

### 3.5.1. WLAN\_WAKE

WLAN\_WAKE is used to wake up the host. And the interrupt function that replaces the regular SDIO D1 interrupt pin.

**Table 6: Pin Definition of WLAN\_WAKE**

| Pin Name  | Pin No. | I/O | Description                                           | Comment                                              |
|-----------|---------|-----|-------------------------------------------------------|------------------------------------------------------|
| WLAN_WAKE | 16      | DO  | Wake up the host by WLAN, and SDIO interrupt function | GPIO_1 connected to WLAN_WAKE must be interruptible. |

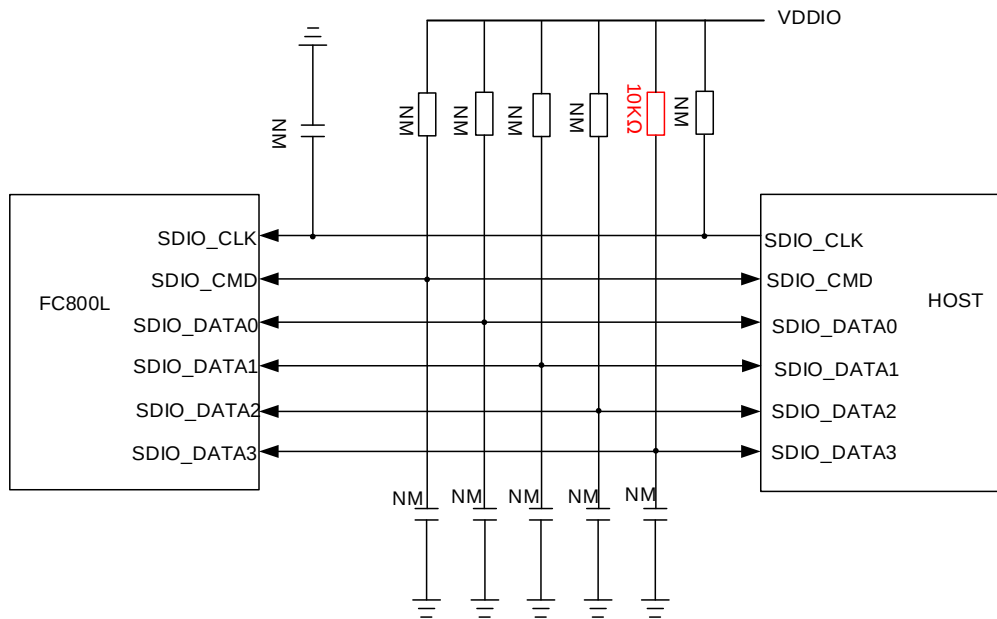
### 3.5.2. SDIO Interface

The following table shows the pin definition of SDIO interface.

**Table 7: Pin Definition of SDIO Interface**

| Pin Name   | Pin No. | I/O | Description     | Comment            |
|------------|---------|-----|-----------------|--------------------|
| SDIO_CMD   | 17      | DIO | SDIO command    | VDDIO power domain |
| SDIO_CLK   | 18      | DI  | SDIO clock      |                    |
| SDIO_DATA3 | 19      | DIO | SDIO data bit 3 |                    |
| SDIO_DATA2 | 20      | DIO | SDIO data bit 2 |                    |
| SDIO_DATA0 | 21      | DIO | SDIO data bit 0 |                    |
| SDIO_DATA1 | 22      | DIO | SDIO data bit 1 |                    |

The following figure shows the SDIO interface connection between FC800L and host.



**Figure 4: SDIO Interface Connection**

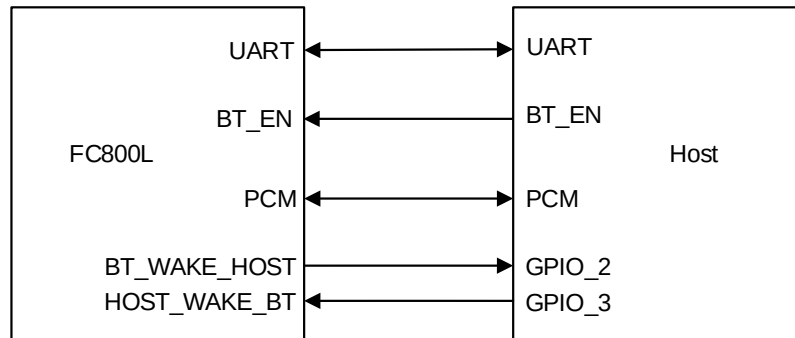
To ensure that the interface design complies with the SDIO 3.0 specification, the following principles are recommended to be adopted:

- Route the SDIO traces in inner-layer of the PCB and the impedance is controlled at  $50 \Omega \pm 10 \%$ ;
- SDIO signals need to be keep away from sensitive signals, such as radio frequency, analog signals, clocks, and DC-DC noise signals;
- The distance between SDIO signals and other signals must be greater than 2 times the trace width, and the busload capacitance must be less than 15 pF.
- SDIO signal traces need to be treated with equal length (the distance between the traces is less than 1 mm). According to the transmission rate, the trace length has the following requirements:
  - 1) As for SDR104 mode, the recommended bus length is less than 50 mm, the internal trace length of the module is 11.36 mm.
  - 2) As for other modes, such as DDR50, SDR100, etc., the recommended bus length is less than 150 mm.

### 3.6. Bluetooth Application Interface

The following figure shows the block diagram of Bluetooth application interface connection between

FC800L and a host.



**Figure 5: Block Diagram of Bluetooth Application Interface Connection**

**NOTE**

GPIO\_2 connected to BT\_WAKE\_HOST must be interruptible.

### 3.6.1. BT\_EN

BT\_EN is used to control the Bluetooth function of FC800L. Bluetooth function will be enabled when BT\_EN is at high level.

**Table 8: Pin Definition of BT\_EN**

| Pin Name | Pin No. | I/O | Description              | Comment      |
|----------|---------|-----|--------------------------|--------------|
| BT_EN    | 38      | DI  | Bluetooth enable control | Active high. |

### 3.6.2. UART Interface

FC800L supports an HCI UART as defined in *Bluetooth Core Specification Version 5.0*. The UART supports hardware flow control, and it is used for data transmission with host. It supports up to 4.0 Mbps baud rates.

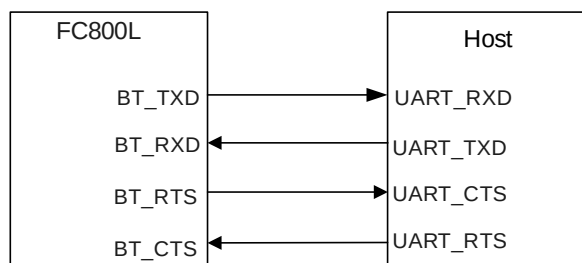
The following table shows the pin definition of UART interface.

**Table 9: Pin Definition of UART Interface**

| Pin Name | Pin No. | I/O | Description                    | Comment            |
|----------|---------|-----|--------------------------------|--------------------|
| BT_TXD   | 40      | DO  | Bluetooth UART transmit        | VDDIO power domain |
| BT_RXD   | 41      | DI  | Bluetooth UART receive         |                    |
| BT_RTS   | 42      | DO  | Bluetooth UART request to send |                    |
| BT_CTS   | 43      | DI  | Bluetooth UART clear to send   |                    |

The voltage range of the Bluetooth UART interface of FC800L is determined by VDDIO. It is necessary to pay attention to whether the voltage range of host and FC800L Bluetooth UART interface is consistent. If necessary, voltage-level translator shall be added.

The following figure shows a reference design for UART interface connection between FC800L and host.



**Figure 6: Reference Design for UART Interface Connection**

### 3.6.3. BT\_WAKE\_HOST\* and HOST\_WAKE\_BT\*

**Table 10: Pin Definition of BT\_WAKEUP\_HOST and HOST\_WAKEUP\_BT**

| Pin Name     | Pin No. | I/O | Description             | Comment            |
|--------------|---------|-----|-------------------------|--------------------|
| HOST_WAKE_BT | 49      | DI  | Host wakes up Bluetooth | VDDIO power domain |
| BT_WAKE_HOST | 50      | DO  | Bluetooth wakes up host |                    |

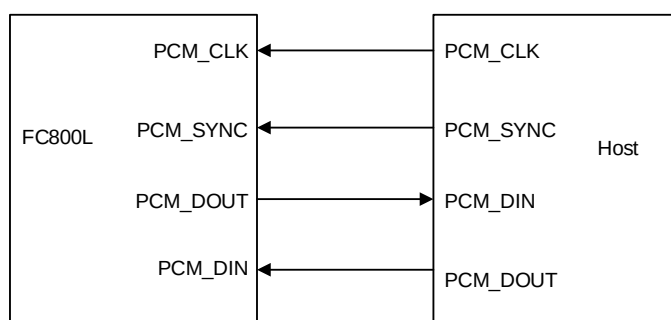
### 3.6.4. PCM Interface\*

PCM interface is used for audio over Bluetooth phone. The following table shows the pin definition of PCM interface.

**Table 11: Pin Definition of PCM Interface**

| Pin Name | Pin No. | I/O | Description         | Comment            |
|----------|---------|-----|---------------------|--------------------|
| PCM_SYNC | 27      | DI  | PCM data frame sync | VDDIO power domain |
| PCM_DIN  | 28      | DI  | PCM data input      |                    |
| PCM_DOUT | 29      | DO  | PCM data output     |                    |
| PCM_CLK  | 30      | DI  | PCM clock           |                    |

The following figure shows the PCM interface connection between FC800L and the host.



**Figure 7: PCM Interface Connection**

## 3.7. Other Interfaces

### 3.7.1. RTC\_CLK

The RTC\_CLK 32.768 kHz is used for internal PMU reference clock.

**Table 12: Pin Definition of RTC\_CLK**

| Pin Name | Pin No. | I/O | Description                     | Comment |
|----------|---------|-----|---------------------------------|---------|
| RTC_CLK  | 31      | DI  | External 32.768 kHz clock input |         |

#### NOTE

RTC\_CLK should be surrounded by GND.

### 3.7.2. CHIP\_EN

The module is enabled by CHIP\_EN.

**Table 13: Pin Definition of CHIP\_EN**

| Pin Name | Pin No. | I/O | Description       | Comment                            |
|----------|---------|-----|-------------------|------------------------------------|
| CHIP_EN  | 15      | DI  | Module enable pin | Active high.<br>VDDIO power domain |

### 3.8. RF Antenna Interfaces

ANT\_BT and ANT\_WIFI is the RF antenna pin, and the RF port requires 50  $\Omega$  characteristic impedance.

#### 3.8.1. Operating Frequency

The operating frequency of FC800L is shown in the following.

**Table 1: Operating Frequency of the Module**

| Feature      | Frequency    | Unit |
|--------------|--------------|------|
| 2.4 GHz WLAN | 2.400–2.4835 | GHz  |
| 5 GHz WLAN   | 5.150–5.850  | GHz  |
| Bluetooth    | 2.402–2.480  | GHz  |

#### 3.8.2. Pin Definition of RF Antenna Interface

Pin definitions of the antenna interface are shown in the following table:

**Table 2: Pin Definition of RF Antenna Interfaces**

| Pin Name | Pin No. | I/O | Description                 | Comment               |
|----------|---------|-----|-----------------------------|-----------------------|
| ANT_BT   | 2       | AIO | Bluetooth antenna interface | 50 $\Omega$ impedance |
| ANT_WIFI | 9       | AIO | Wi-Fi antenna interface 0   | 50 $\Omega$ impedance |

#### 3.8.3. Reference Design of RF Antenna Interfaces

FC800L module provides an RF antenna pin for Wi-Fi & Bluetooth antenna connection. The RF trace in host PCB connected to the module's RF antenna pin should be microstrip line or other types of RF trace, with characteristic impedance close to 50  $\Omega$ . FC800L module comes with grounding pins which are next to the antenna pin to give a better grounding.

A reference circuit for the RF antenna interface is shown below. It is recommended to reserve a  $\pi$ -type matching circuit for better RF performance, and ESD protection devices are designed at the same time. Matching components C1, R1, L1~L4 and protection devices D1, D2 should be placed as close as possible to the antenna. Inductors (L1~L4) are not installed by default.

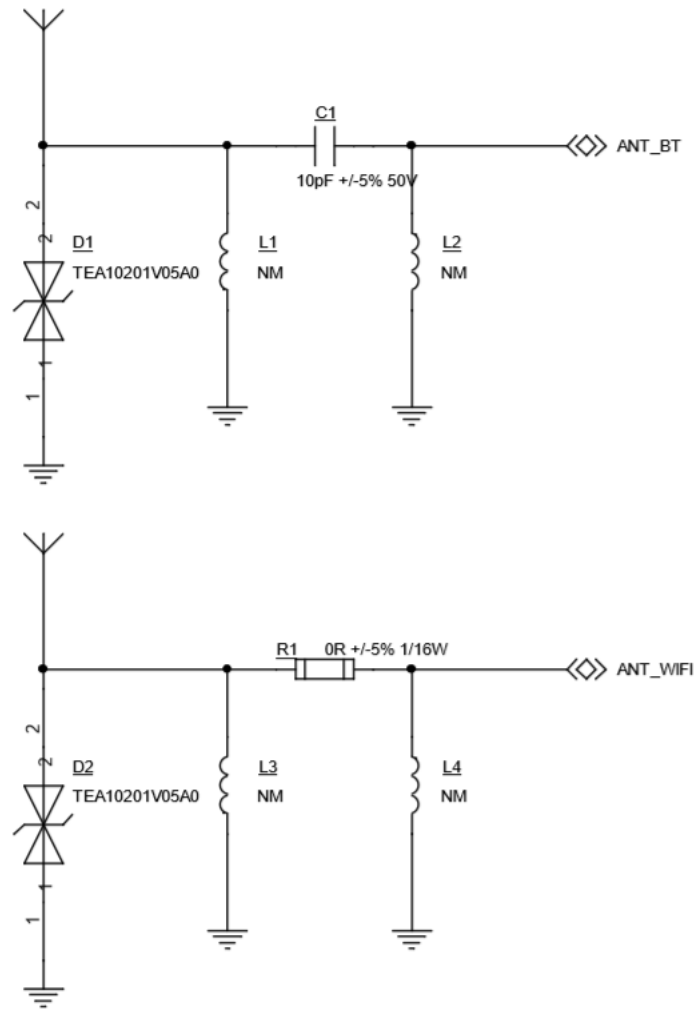
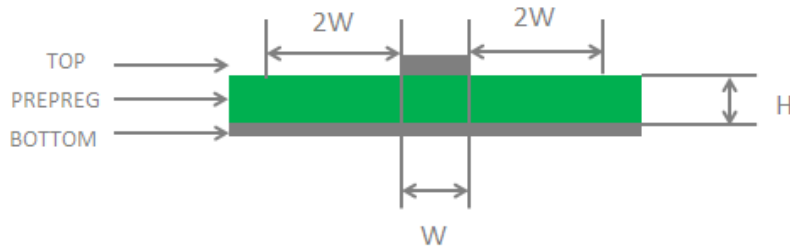


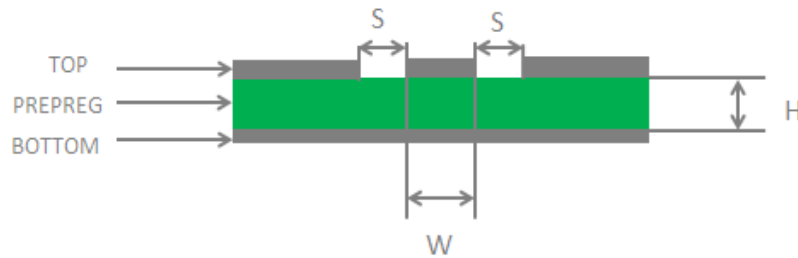
Figure 8: Reference Circuit for RF Antenna Interfaces

### 3.8.4. Reference Design of RF Layout

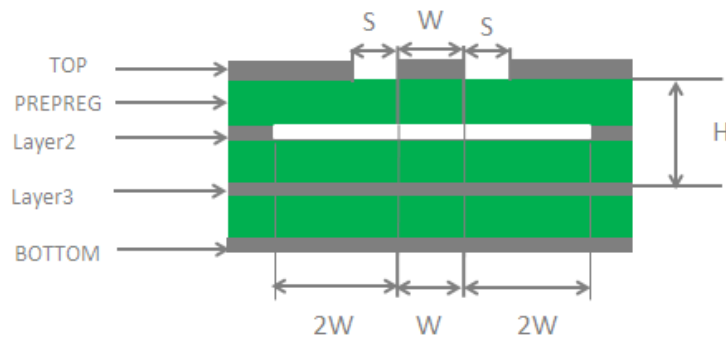
For user's PCB, the characteristic impedance of all RF traces should be controlled to  $50\ \Omega$ . The impedance of the RF traces is usually determined by the trace width ( $W$ ), the materials' dielectric constant, the height from the reference ground to the signal layer ( $H$ ), and the spacing between RF traces and grounds ( $S$ ). Microstrip or coplanar waveguide is typically used in RF layout to control characteristic impedance. The following are reference designs of microstrip or coplanar waveguide with different PCB structures.



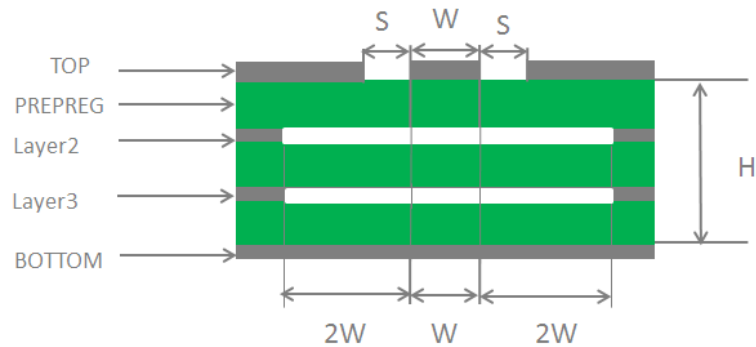
**Figure 9: Microstrip Design on a 2-layer PCB**



**Figure 10: Coplanar Waveguide Design on a 2-layer PCB**



**Figure 11: Coplanar Waveguide Design on a 4-layer PCB (Layer 3 as Reference Ground)**



**Figure 12: Coplanar Waveguide Design on a 4-layer PCB (Layer 4 as Reference Ground)**

In order to ensure RF performance and reliability, the following principles should be complied with in RF layout design:

- Use an impedance simulation tool to accurately control the characteristic impedance of RF traces to 50  $\Omega$ .
- The GND pins adjacent to RF pins should not be designed as thermal relief pads, and should be fully connected to ground.
- The distance between the RF pins and the RF connector should be as short as possible, and all the right-angle traces should be changed to curved ones. The recommended trace angle is 135°.
- There should be clearance under the signal pin of the antenna connector or solder joint.
- The reference ground of RF traces should be complete. Meanwhile, adding some ground vias around RF traces and the reference ground could help to improve RF performance. The distance between the ground vias and RF traces should be no less than two times the width of RF signal traces ( $2 \times W$ ).
- Keep RF traces away from interference sources, and avoid intersection and paralleling between traces on adjacent layers.

For more details about RF layout, see **document**

### 3.8.5. Antenna Requirements

The following tables show the requirements on antenna cables and antennas.

**Table 3: Antenna Cable Requirements**

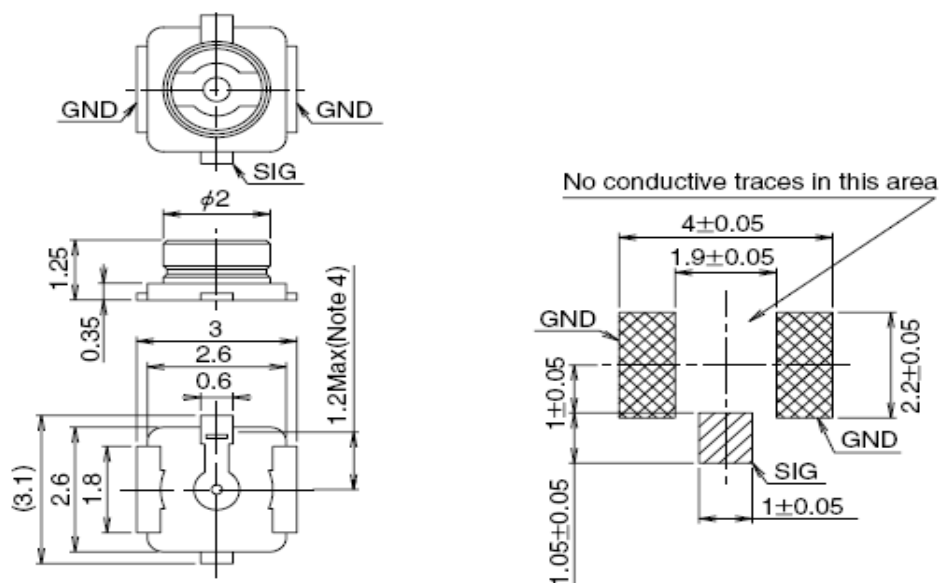
| Type             | Requirements                |
|------------------|-----------------------------|
| 2.400–2.4835 GHz | Cable insertion loss: <1 dB |
| 5.150–5.850 GHz  | Cable insertion loss: <1 dB |

**Table 4: Antenna Requirements**

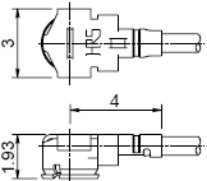
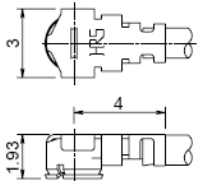
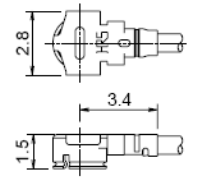
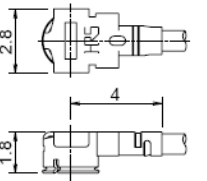
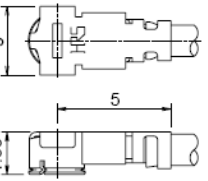
| Type                         | Requirements                |
|------------------------------|-----------------------------|
| Frequency Range (GHz)        | 2.400–2.4835<br>5.150–5.850 |
| VSWR                         | < 2:1 recommended           |
| Gain (dBi)                   | Typical 1                   |
| Max Input Power (W)          | 50                          |
| Input Impedance ( $\Omega$ ) | 50                          |
| Polarization Type            | Vertical                    |

### 3.8.6. Recommended RF Connector for Antenna Installation

If RF connector is used for antenna connection, it is recommended to use U.FL-R-SMT connector provided by Hirose.

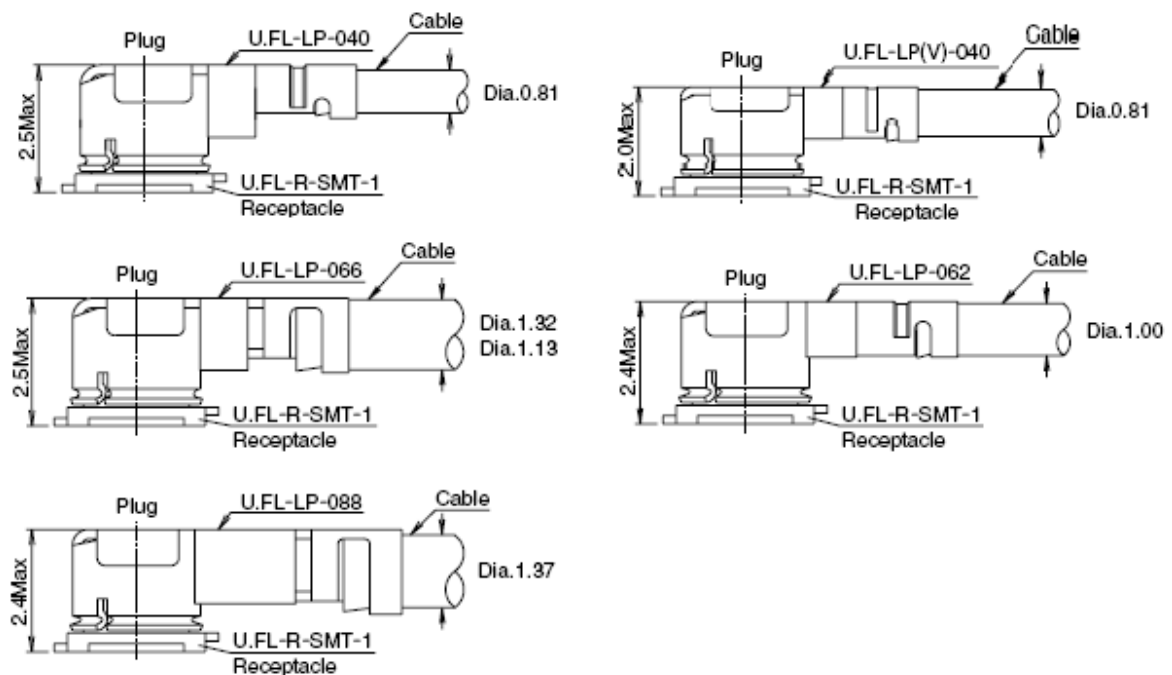

**Figure 13: Dimensions of the U.FL-R-SMT Connector (Unit: mm)**

U.FL-LP serial connectors listed in the following figure can be used to match the U.FL-R-SMT.

| Part No.         | U.FL-LP-040                                                                       | U.FL-LP-066                                                                       | U.FL-LP(V)-040                                                                    | U.FL-LP-062                                                                         | U.FL-LP-088                                                                         |
|------------------|-----------------------------------------------------------------------------------|-----------------------------------------------------------------------------------|-----------------------------------------------------------------------------------|-------------------------------------------------------------------------------------|-------------------------------------------------------------------------------------|
|                  |  |  |  |  |  |
| Mated Height     | 2.5mm Max.<br>(2.4mm Nom.)                                                        | 2.5mm Max.<br>(2.4mm Nom.)                                                        | 2.0mm Max.<br>(1.9mm Nom.)                                                        | 2.4mm Max.<br>(2.3mm Nom.)                                                          | 2.4mm Max.<br>(2.3mm Nom.)                                                          |
| Applicable cable | Dia. 0.81mm<br>Coaxial cable                                                      | Dia. 1.13mm and<br>Dia. 1.32mm<br>Coaxial cable                                   | Dia. 0.81mm<br>Coaxial cable                                                      | Dia. 1mm<br>Coaxial cable                                                           | Dia. 1.37mm<br>Coaxial cable                                                        |
| Weight (mg)      | 53.7                                                                              | 59.1                                                                              | 34.8                                                                              | 45.5                                                                                | 71.7                                                                                |
| RoHS             | YES                                                                               |                                                                                   |                                                                                   |                                                                                     |                                                                                     |

**Figure 14: Mechanicals of U.FL-LP Connectors (Unit: mm)**

The following figure describes the space factor of mated connector



**Figure 15: Space Factor of Mated Connector (Unit: mm)**

For more details, please visit <http://www.hirose.com>.

# 4 Reliability, Radio and Electrical Characteristic

## 4.1. General Description

This chapter mainly introduces the electrical characteristics and radio frequency characteristics of FC800L, the specific content is as follows:

- Absolute maximum ratings
- I/O interface characteristics
- Power consumption
- RF performance
- ESD protection
- Operating and storage temperature

## 4.2. Electrical Characteristics

Table 5: Absolute Maximum Ratings

| Parameter                 | Min. | Max. | Unit |
|---------------------------|------|------|------|
| VBAT                      | -0.5 | 3.63 | V    |
| VDDIO                     | -0.5 | 3.63 | V    |
| Digital I/O Input Voltage | -0.5 | 3.63 | V    |

The following table shows the recommended operating conditions of FC800L module.

**Table 6: Recommended Operating Conditions**

| Parameter         | Min. | Typ. | Max. | Unit |
|-------------------|------|------|------|------|
| V <sub>BAT</sub>  | 2.97 | 3.3  | 3.63 | V    |
| V <sub>DDIO</sub> | 1.62 | 1.8  | 1.98 | V    |

### 4.3. I/O Interface Characteristics

The following table shows the general DC electrical characteristics over recommended operating conditions (unless otherwise specified).

**Table 7: General DC Electrical Characteristics**

| Symbol          | Parameter                 | Min.                   | Max.                   | Unit |
|-----------------|---------------------------|------------------------|------------------------|------|
| V <sub>IH</sub> | High-level Input Voltage  | $0.65 \times V_{DDIO}$ | $V_{DDIO} + 0.3$       | V    |
| V <sub>IL</sub> | Low-level Input Voltage   | -0.3                   | $0.35 \times V_{DDIO}$ | V    |
| V <sub>OH</sub> | High-level Output Voltage | $V_{DDIO} - 0.2$       | $V_{DDIO} + 0.3$       | V    |
| V <sub>OL</sub> | Low-level Output Voltage  | -0.3                   | 0.2                    | V    |

## 4.4. Current Consumption

**Table 8: Current Consumption of the Module (Normal Operation)**

| Description | Conditions             | VBAT (3.3 V) | VDDIO (1.8 V) | Unit |
|-------------|------------------------|--------------|---------------|------|
| Shutdown    | AT+QWIFI=0             | TBD          | TBD           | μA   |
| Idle        | AT+QWIFI=1             | TBD          | TBD           | mA   |
| 802.11b     | TX (2.4 GHz) 1 Mbps    | 241.50       | 0.03          | mA   |
|             | TX (2.4 GHz) 11 Mbps   | 203.50       | 0.07          | mA   |
| 802.11g     | TX (2.4 GHz) 6 Mbps    | 266.50       | 0.04          | mA   |
|             | TX (2.4 GHz) 54 Mbps   | 165.50       | 0.04          | mA   |
| 802.11n     | TX (2.4 GHz) HT20 MCS0 | 265.50       | 0.04          | mA   |
|             | TX (2.4 GHz) HT20 MCS7 | 158.00       | 0.05          | mA   |
|             | TX (2.4 GHz) HT40 MCS0 | 261.00       | 0.04          | mA   |
|             | TX (2.4 GHz) HT40 MCS7 | 161.00       | 0.02          | mA   |
|             | TX (5 GHz) HT20 MCS0   | 441.50       | 0.04          | mA   |
|             | TX (5 GHz) HT20 MCS7   | 250.00       | 0.05          | mA   |
|             | TX (5 GHz) HT40 MCS0   | 443.50       | 0.04          | mA   |
|             | TX (5 GHz) HT40 MCS7   | 277.50       | 0.01          | mA   |
| 802.11a     | TX (5 GHz) 6 Mbps      | 443.00       | 0.04          | mA   |
|             | TX (5 GHz) 54 Mbps     | 264.50       | 0.04          | mA   |
| 802.11ac    | TX (5 GHz) VHT20 MCS0  | 483.00       | 0.03          | mA   |
|             | TX (5 GHz) VHT20 MCS8  | 329.50       | 0.02          | mA   |
|             | TX (5 GHz) VHT40 MCS0  | 448.00       | 0.04          | mA   |
|             | TX (5 GHz) VHT40 MCS9  | 225.00       | 0.02          | mA   |

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|                       |        |      |    |
|-----------------------|--------|------|----|
| TX (5 GHz) VHT80 MCS0 | 431.50 | 0.04 | mA |
| TX (5 GHz) VHT80 MCS9 | 167.50 | 0.02 | mA |

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## 4.5. RF Performances

The following tables summarize the transmitting and receiving performances of FC800L.

### 4.5.1. Wi-Fi Performance

**Table 14: Conducted RF Output Power at 2.4 GHz**

| Standard             | Min. | Typ. | Unit |
|----------------------|------|------|------|
| 802.11b @ 1 Mbps     | 14   | 16   | dBm  |
| 802.11b @ 11 Mbps    | 14   | 16   | dBm  |
| 802.11g @ 6 Mbps     | 15   | 17   | dBm  |
| 802.11g @ 54 Mbps    | 13   | 15   | dBm  |
| 802.11n, HT20 @ MCS0 | 15   | 17   | dBm  |
| 802.11n, HT20 @ MCS7 | 12   | 14   | dBm  |
| 802.11n, HT40 @ MCS0 | 14   | 16   | dBm  |
| 802.11n, HT40 @ MCS7 | 12   | 14   | dBm  |

**Table 15: Conducted RF Output Power at 5 GHz**

| Standard               | Min. | Typ. | Unit |
|------------------------|------|------|------|
| 802.11a @ 6 Mbps       | 14   | 17   | dBm  |
| 802.11a @ 54 Mbps      | 12   | 15   | dBm  |
| 802.11n, HT20 @ MCS0   | 14   | 17   | dBm  |
| 802.11n, HT20 @ MCS7   | 11   | 14   | dBm  |
| 802.11n, HT40 @ MCS0   | 13   | 16   | dBm  |
| 802.11n, HT40 @ MCS7   | 11   | 14   | dBm  |
| 802.11ac, VHT20 @ MCS0 | 14   | 17   | dBm  |

|                        |    |    |     |
|------------------------|----|----|-----|
| 802.11ac, VHT20 @ MCS8 | 10 | 13 | dBm |
| 802.11ac, VHT40 @ MCS0 | 13 | 16 | dBm |
| 802.11ac, VHT40 @ MCS9 | 9  | 12 | dBm |
| 802.11ac, VHT80 @ MCS0 | 11 | 14 | dBm |
| 802.11ac, VHT80 @ MCS9 | 8  | 11 | dBm |

**Table 16: Conducted RF Receiving Sensitivity at 2.4 GHz**

| Standard            | Receiving Sensitivity (Typ.) |
|---------------------|------------------------------|
| 802.11b, 1 Mbps     | -95.5 dBm                    |
| 802.11b, 11 Mbps    | -87.0 dBm                    |
| 802.11g, 6 Mbps     | -93.0 dBm                    |
| 802.11g, 54 Mbps    | -76.0 dBm                    |
| 802.11n, HT20, MCS0 | -92.5 dBm                    |
| 802.11n, HT20, MCS7 | -74.5 dBm                    |
| 802.11n, HT40, MCS0 | -89.0 dBm                    |
| 802.11n, HT40, MCS7 | -70.5 dBm                    |

**Table 17: Conducted RF Receiving Sensitivity at 5 GHz**

| Standard            | Receiving Sensitivity (Typ.) |
|---------------------|------------------------------|
| 802.11a, 6 Mbps     | -94.0 dBm                    |
| 802.11a, 54 Mbps    | -75.0 dBm                    |
| 802.11n, HT20, MCS0 | -93.0 dBm                    |
| 802.11n, HT20, MCS7 | -75.0 dBm                    |
| 802.11n, HT40, MCS0 | -89.0 dBm                    |
| 802.11n, HT40, MCS7 | -71.0 dBm                    |

|                       |           |
|-----------------------|-----------|
| 802.11ac, VHT20, MCS0 | -92.5 dBm |
| 802.11ac, VHT20, MCS8 | -69.5 dBm |
| 802.11ac, VHT40, MCS0 | -89.0 dBm |
| 802.11ac, VHT40, MCS9 | -64.5 dBm |
| 802.11ac, VHT80, MCS0 | -84.0 dBm |
| 802.11ac, VHT80, MCS9 | -59.0 dBm |

#### 4.5.2. Bluetooth Performance

The following table shows the Bluetooth transmitting and receiving performance of FC800L module.

| Standard             | Transmitting Power | Receiving Sensitivity | Unit |
|----------------------|--------------------|-----------------------|------|
| BR                   | 6.8                | -90.0                 | dBm  |
| EDR( $\pi/4$ -DQPSK) | 5.1                | -90.5                 | dBm  |
| EDR(8-DPSK)          | 5.1                | -85.5                 | dBm  |
| BLE(1M)              | 6.7                | -98.5                 | dBm  |
| BLE(2M)              | 6.7                | -96.0                 | dBm  |
| S=2                  | 6.7                | -100.5                | dBm  |
| S=8                  | 6.7                | -103.5                | dBm  |

## 4.6. Electrostatic Discharge

Static electricity occurs naturally and it may damage the module. Therefore, applying proper ESD countermeasures and handling methods is imperative. For example, wear anti-static gloves during the development, production, assembly and testing of the module; add ESD protection components to the ESD sensitive interfaces and points in the product design.

**Table 18: Electrostatics Discharge Characteristics (25 °C, 45 % Relative Humidity; Unit: kV)**

| Tested Interfaces | Contact Discharge | Air Discharge | Unit |
|-------------------|-------------------|---------------|------|
| VBAT、GND          | 2                 | 12            | kV   |
| ANT_BT、ANT_WIFI   | 5                 | 10            | kV   |
| Other Interfaces  | 2                 | 2             | kV   |

# 5 Mechanical Information

This chapter describes the mechanical dimensions of FC800L. All dimensions are measured in millimeter (mm), and the dimensional tolerances are  $\pm 0.2$  mm unless otherwise specified.

## 5.1. Mechanical Dimensions

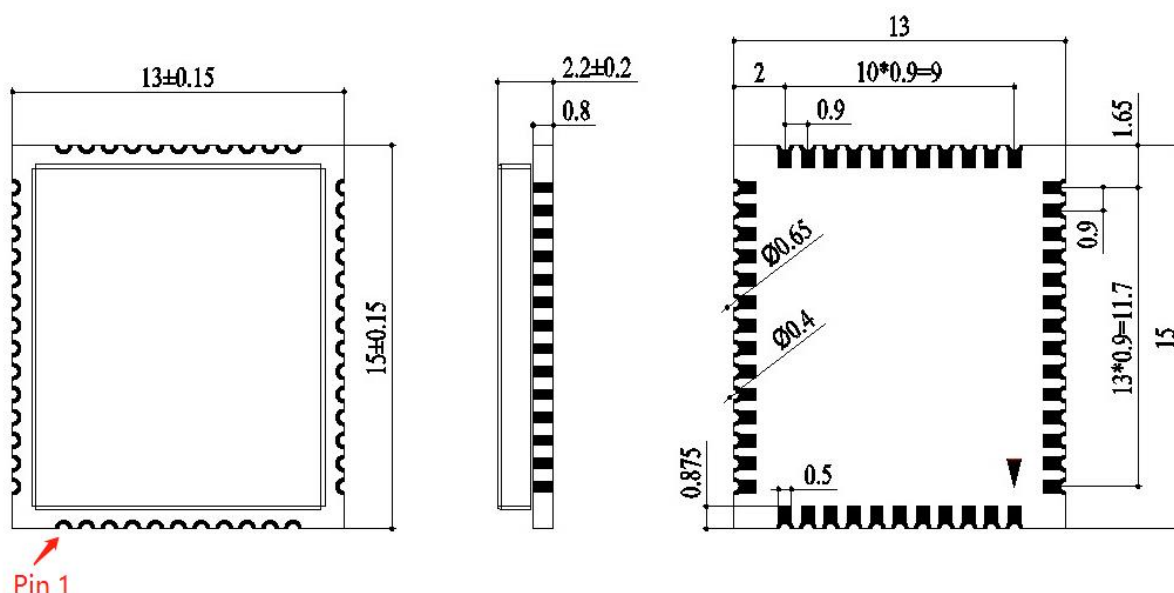


Figure 16: Top and Side Dimensions (Top and Side View)

### NOTE

The package warpage level of the module conforms to JEITA ED-7306 standard.

## 5.2. Recommended Footprint

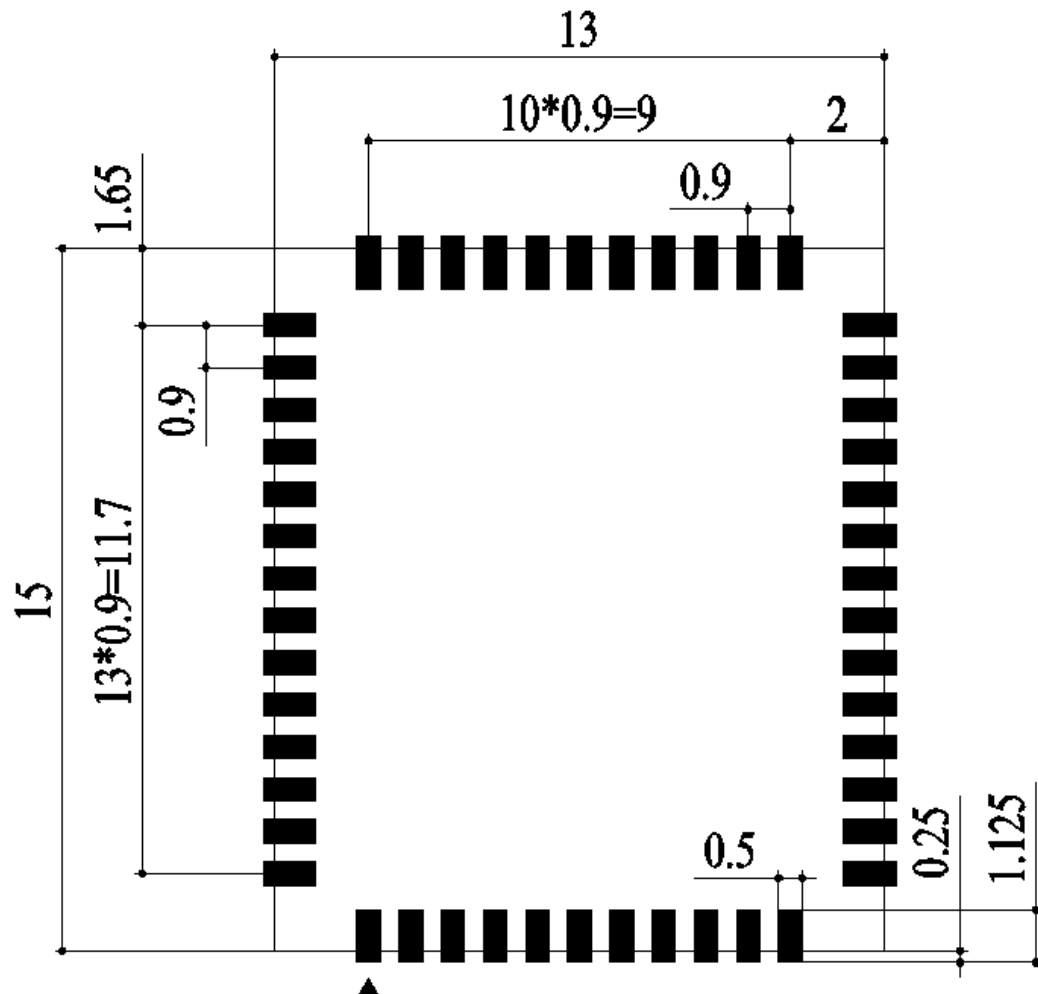


Figure 17: Recommended Footprint (Top View)

### NOTE

1. For easy maintenance of this module, keep at least 3 mm between the module and other components on the motherboard.
2. Keep all RESERVED pins open.

### 5.3. Top and Bottom Views

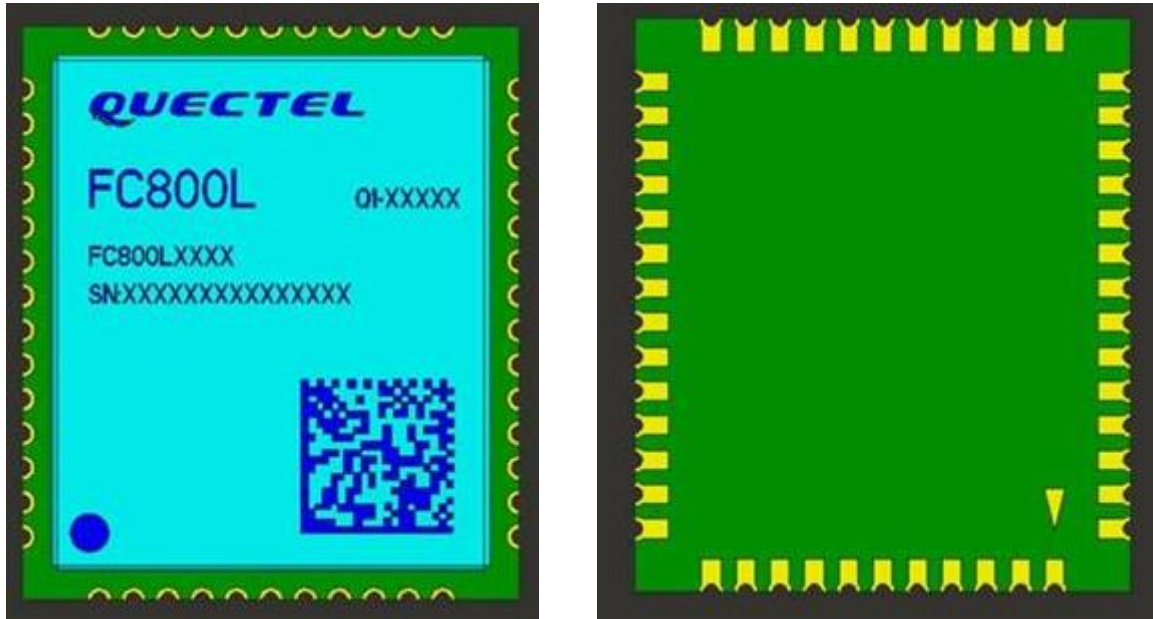


Figure 18: Top and Bottom Views of the Module

**NOTE**

Images above are for illustration purpose only and may differ from the actual module. For authentic appearance and label, please refer to the module received from Quectel.

# 6 Storage, Manufacturing and Packaging

## 6.1. Storage Conditions

The module is provided with vacuum-sealed packaging. MSL of the module is rated as 3. The storage requirements are shown below.

1. Recommended Storage Condition: The temperature should be  $23 \pm 5$  °C and the relative humidity should be 35–60 %.
2. The storage life (in vacuum-sealed packaging) is 12 months in Recommended Storage Condition.
3. The floor life of the module is 168 hours <sup>2</sup> in a plant where the temperature is  $23 \pm 5$  °C and relative humidity is below 60 %. After the vacuum-sealed packaging is removed, the module must be processed in reflow soldering or other high-temperature operations within 168 hours. Otherwise, the module should be stored in an environment where the relative humidity is less than 10 % (e.g. a drying cabinet).
4. The module should be pre-baked to avoid blistering, cracks and inner-layer separation in PCB under the following circumstances:
  - The module is not stored in Recommended Storage Condition;
  - Violation of the third requirement above occurs;
  - Vacuum-sealed packaging is broken, or the packaging has been removed for over 24 hours;
  - Before module repairing.
5. If needed, the pre-baking should follow the requirements below:
  - The module should be baked for 8 hours at  $120 \pm 5$  °C;
  - All modules must be soldered to PCB within 24 hours after the baking, otherwise they should be put in a dry environment such as in a drying oven.

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<sup>2</sup> This floor life is only applicable when the environment conforms to *IPC/JEDEC J-STD-033*. It is recommended to start the solder reflow process within 24 hours after the package is removed if the temperature and moisture do not conform to, or are not sure to conform to *IPC/JEDEC J-STD-033*. And do not remove the packages of tremendous modules if they are not ready for soldering.

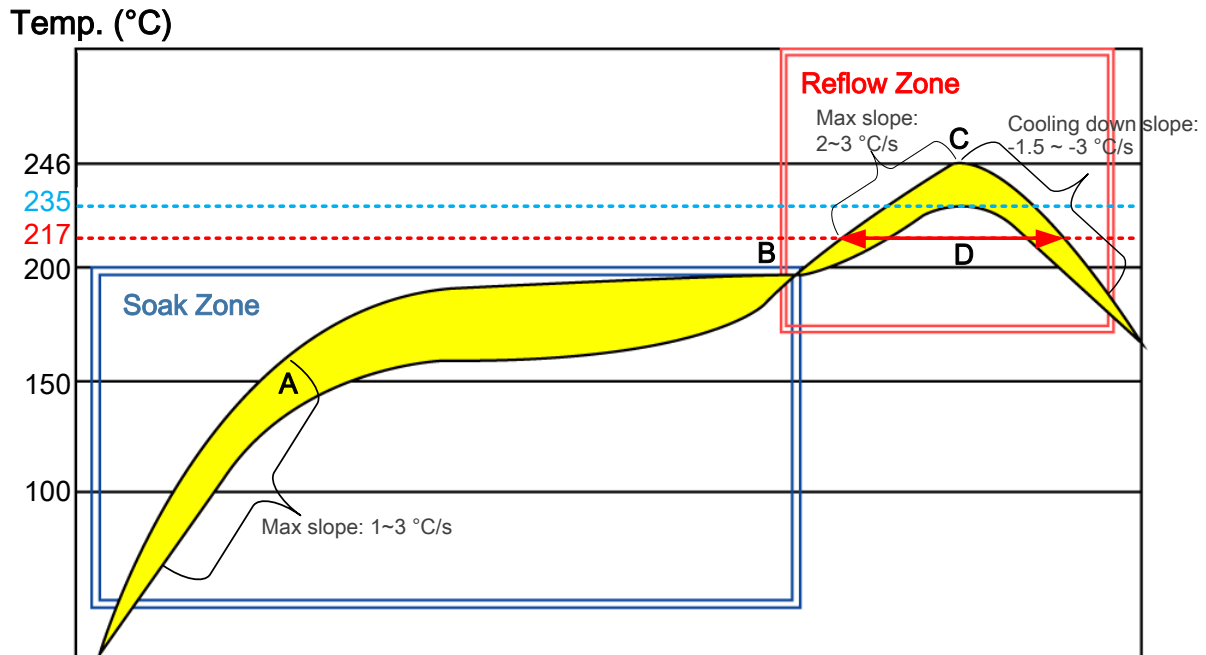
**NOTE**

1. To avoid blistering, layer separation and other soldering issues, extended exposure of the module to the air is forbidden.
2. Take out the module from the package and put it on high-temperature-resistant fixtures before baking. All modules must be soldered to PCB within 24 hours after the baking, otherwise put them in the drying oven. If shorter baking time is desired, see *IPC/JEDEC J-STD-033* for the baking procedure.
3. Pay attention to ESD protection, such as wearing anti-static gloves, when touching the modules.

## 6.2. Manufacturing and Soldering

Push the squeegee to apply the solder paste on the surface of stencil, thus making the paste fill the stencil openings and then penetrate to the PCB. Apply proper force on the squeegee to produce a clean stencil surface on a single pass. To guarantee module soldering quality, the thickness of stencil for the module is recommended to be 0.13–0.15 mm. For more details, see **document [2]**

The peak reflow temperature should be 238–246 °C, with 246 °C as the absolute maximum reflow temperature. To avoid damage to the module caused by repeated heating, it is strongly recommended that the module should be mounted only after reflow soldering for the other side of PCB has been completed. The recommended reflow soldering thermal profile (lead-free reflow soldering) and related parameters are shown below.



**Figure 19: Recommended Reflow Soldering Thermal Profile**

**Table 19: Recommended Thermal Profile Parameters**

| Factor                                         | Recommendation   |
|------------------------------------------------|------------------|
| <b>Soak Zone</b>                               |                  |
| Max slope                                      | 1–3 °C/s         |
| Soak time (between A and B: 150 °C and 200 °C) | 70–120 s         |
| <b>Reflow Zone</b>                             |                  |
| Max slope                                      | 2–3 °C/s         |
| Reflow time (D: over 217 °C)                   | 40–70 s          |
| Max temperature                                | 235 °C to 246 °C |
| Cooling down slope                             | -1.5 to -3 °C/s  |
| <b>Reflow Cycle</b>                            |                  |
| Max reflow cycle                               | 1                |

**NOTE**

1. During manufacturing and soldering, or any other processes that may contact the module directly, NEVER wipe the module's shielding can with organic solvents, such as acetone, ethyl alcohol, isopropyl alcohol, trichloroethylene, etc. Otherwise, the shielding can may become rusted.
2. The shielding can for the module is made of Cupro-Nickel base material. It is tested that after 12 hours' Neutral Salt Spray test, the laser engraved label information on the shielding can is still clearly identifiable and the QR code is still readable, although white rust may be found.
3. If a conformal coating is necessary for the module, do NOT use any coating material that may chemically react with the PCB or shielding cover, and prevent the coating material from flowing into the module.

## 6.3. Packaging Specifications

The module adopts carrier tape packaging and details are as follow:

### 6.3.1. Carrier Tape

Dimension details are as follow:

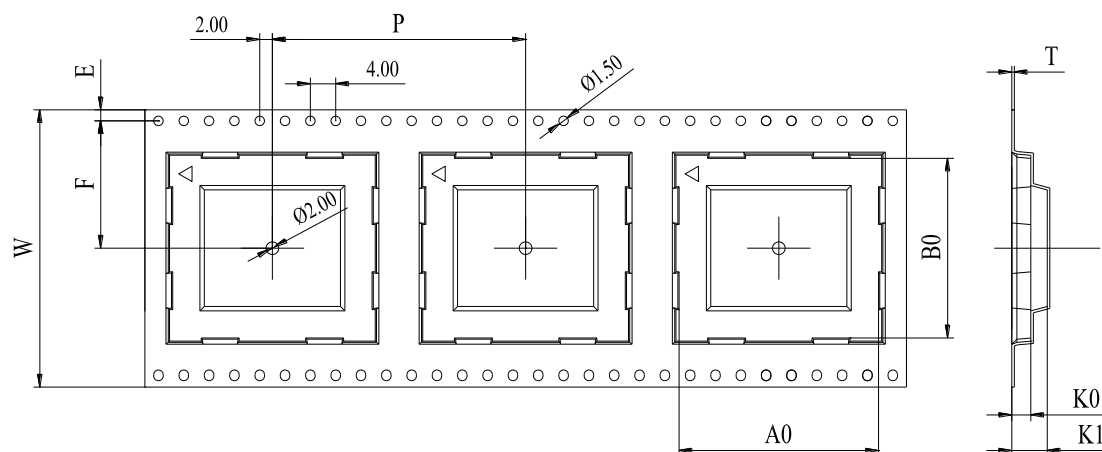


Figure 20: Carrier Tape Dimension Drawing

Table 20: Carrier Tape Dimension Table (Unit: mm)

| W  | P  | T   | A0   | B0   | K0  | K1  | F    | E    |
|----|----|-----|------|------|-----|-----|------|------|
| 32 | 20 | 0.4 | 13.4 | 15.4 | 2.7 | 5.4 | 14.2 | 1.75 |

### 6.3.2. Plastic Reel

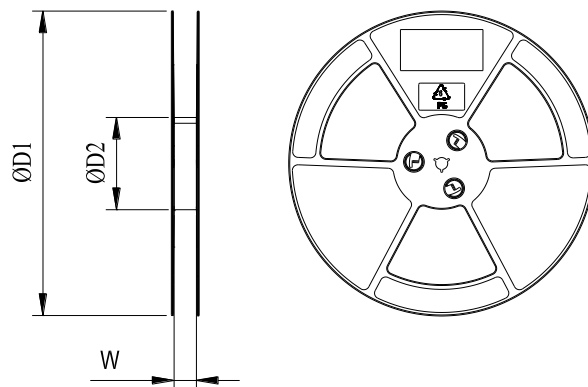
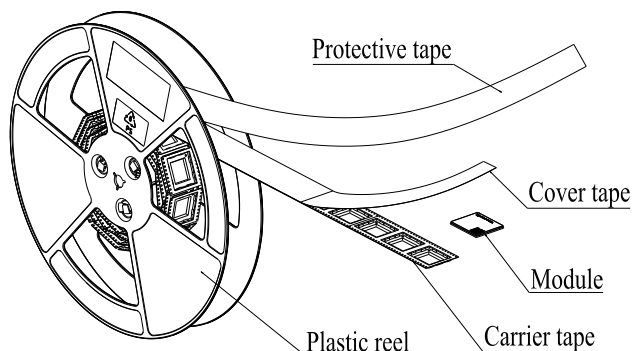


Figure 21: Plastic Reel Dimension Drawing

Table 21: Plastic Reel Dimension Table (Unit: mm)

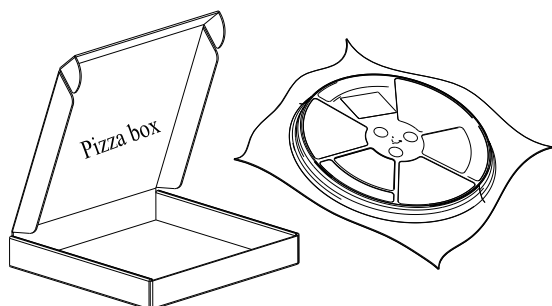
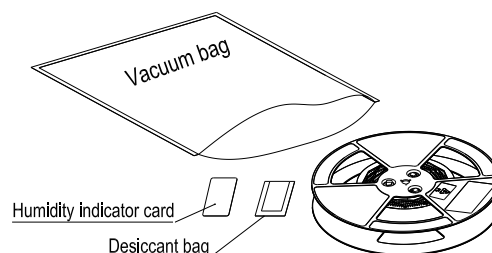
| ØD1 | ØD2 | W    |
|-----|-----|------|
| 330 | 100 | 32.5 |

### 6.3.3. Packaging Process



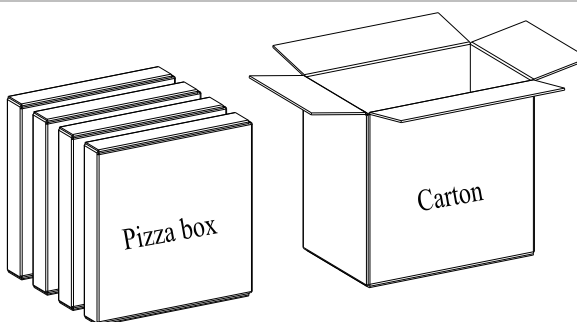
Place the module into the carrier tape and use the cover tape to cover them; then wind the heat-sealed carrier tape to the plastic reel and use the protective tape for protection. One plastic reel can load 500 modules.

Place the packaged plastic reel, humidity indicator card and desiccant bag into a vacuum bag, then vacuumize it.



Place the vacuum-packed plastic reel into a pizza box.

Put 4 pizza boxes into 1 carton and seal it. One carton can pack 2000 modules.



**Figure 22: Packaging Process**

# 7 Appendix References

**Table 22: Related Documents**

| Document Name                                     |
|---------------------------------------------------|
| [1] Quectel_UMTS&LTE_EVB_User_Guide               |
| [2] Quectel_Module_Secondary_SMT_Application_Note |

**Table 23: Terms and Abbreviations**

| Abbreviation | Description                                       |
|--------------|---------------------------------------------------|
| BPSK         | Binary Phase Shift Keying                         |
| BT           | Bluetooth                                         |
| CCK          | Complementary Code Keying                         |
| CTS          | Clear to Send                                     |
| GND          | Ground                                            |
| HCI          | Host Controller Interface                         |
| IEEE         | Institute of Electrical and Electronics Engineers |
| $I_{IL}$     | Input Leakage Current                             |
| I/O          | Input/Output                                      |
| LNA          | Low-Noise Amplifier                               |
| LTE          | Long Term Evolution                               |
| Mbps         | Megabits per second                               |
| MCS          | Modulation and Coding Scheme                      |
| PA           | Power Amplifier                                   |

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|       |                                             |
|-------|---------------------------------------------|
| PCB   | Printed Circuit Board                       |
| PCM   | Pulse Code Modulation                       |
| QAM   | Quadrature Amplitude Modulation             |
| QPSK  | Quadrature Phase Shift Keying               |
| RF    | Radio Frequency                             |
| RoHS  | Restriction of Hazardous Substances         |
| RTS   | Request to Send                             |
| RX    | Receive                                     |
| TBD   | To Be Determined                            |
| TX    | Transmit                                    |
| UART  | Universal Asynchronous Receiver/Transmitter |
| VHT   | Very High Throughput                        |
| Wi-Fi | Wireless-Fidelity                           |
| WLAN  | Wireless Local Area Network                 |

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